

CLAIMS

What is claimed is:

1. A method for measuring anisotropic conductive film bond contact resistance on an liquid crystal display panel, the method comprising the steps of:
 - providing a test pad array on a surface of the liquid crystal display panel;
 - electrically connecting the test pad array to a group of terminal pads disposed on the surface of the panel, the group of terminal pads electrically connected to a first electronic device with anisotropic conductive film bonds; and
 - measuring a contact resistance of at least one of the anisotropic conductive film bonds using the test pad array.
2. The method according to claim 1, wherein the test pad array is disposed in a peripheral region of the liquid crystal display panel.
3. The method according to claim 1, wherein the test pad array is disposed in a space next to the group of terminal pads.
4. The method according to claim 1, further comprising the steps of:
 - providing a dummy lead array on the surface of the liquid crystal display panel, the dummy lead array electrically connecting a second electronic device to the panel;
 - electrically connecting the dummy lead array to the test pad array; and

measuring a contact resistance of at least one anisotropic conductive film bond associated with the second electronic device using portions of the test pad array electrically connected to the dummy lead array.

5. The method according to claim 4, wherein the first electronic device is selected from the group consisting of an integrated circuit chip, a flexible printed circuit, a tape-carrier-package and a chip-on-film.

6. The method according to claim 5, wherein the second electronic device is selected from the group consisting of an integrated circuit chip, a flexible printed circuit, a tape-carrier-package and a chip-on-film.

7. The method according to claim 4, wherein the second electronic device is selected from the group consisting of an integrated circuit chip, a flexible printed circuit, a tape-carrier-package and a chip-on-film.

8. The method according to claim 1, wherein the first electronic device is selected from the group consisting of an integrated circuit chip, a flexible printed circuit, a tape-carrier-package and a chip-on-film.

9. A liquid crystal display panel, comprising:
a panel;
a group of terminal pads disposed on a surface of the panel;

a first electronic device;

anisotropic conductive film bonds electrically connecting the first electronic device to the group of terminal pads;

a test pad array disposed on the surface of the panel, the test pad array electrically connected to the group of terminal pads;

wherein the test pad array allows contact resistance measuring of at least one of the anisotropic conductive film bonds.

10. The liquid crystal display panel according to claim 9, wherein the test pad array is disposed in a peripheral region of the panel.

11. The liquid crystal display panel according to claim 9, wherein the test pad array is disposed in a space next to the group of terminal pads.

12. The liquid crystal display panel according to claim 9, further comprising:

a dummy lead array disposed on the surface of the panel, the dummy lead array for electrically connecting a second electronic device to the panel, the dummy lead array electrically connected to the test pad array,

wherein the dummy lead array allows contact resistance measuring of at least one anisotropic conductive film bond associated with the second electronic device using portions of the test pad array electrically connected to the dummy lead array.

13. The liquid crystal display panel according to claim 12, wherein the first electronic device is selected from the group consisting of an integrated circuit chip, a flexible printed circuit, a tape-carrier-package and a chip-on-film.

14. The liquid crystal display panel according to claim 13, wherein the second electronic device is selected from the group consisting of an integrated circuit chip, a flexible printed circuit, a tape-carrier-package and a chip-on-film.

15. The liquid crystal display panel according to claim 12, wherein the second electronic device is selected from the group consisting of an integrated circuit chip, a flexible printed circuit, a tape-carrier-package and a chip-on-film.

16. The liquid crystal display panel according to claim 9, wherein the first electronic device is selected from the group consisting of an integrated circuit chip, a flexible printed circuit, a tape-carrier-package and a chip-on-film.